

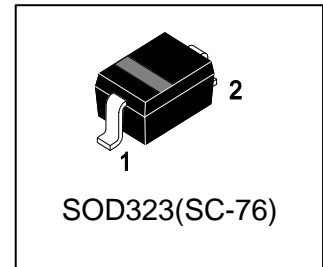
# LBAS20HT1G

## S-LBAS20HT1G

High Voltage Switching Diode

### 1. FEATURES

- We declare that the material of product compliance with RoHS requirements and Halogen Free.
- S- prefix for automotive and other applications requiring unique site and control change requirements; AEC-Q101 qualified and PPAP capable.



### 2. DEVICE MARKING AND ORDERING INFORMATION

Device	Marking	Shipping
LBAS20HT1G	JR	3000/Tape&Reel
LBAS20HT3G	JR	10000/Tape&Reel

### 3. MAXIMUM RATINGS (Ta = 25°C)

Parameter	Symbol	Limits	Unit
Continuous Reverse Voltage	VR	200	V
Peak Forward Current	IF	200	mA
Peak Forward Surge Current	IFM(surge)	625	mA

### 4.THERMAL CHARACTERISTICS

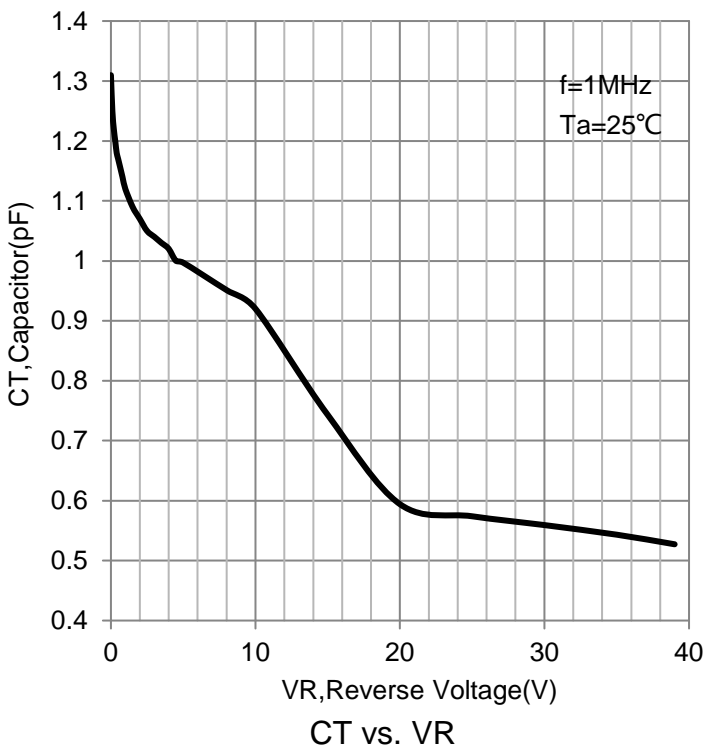
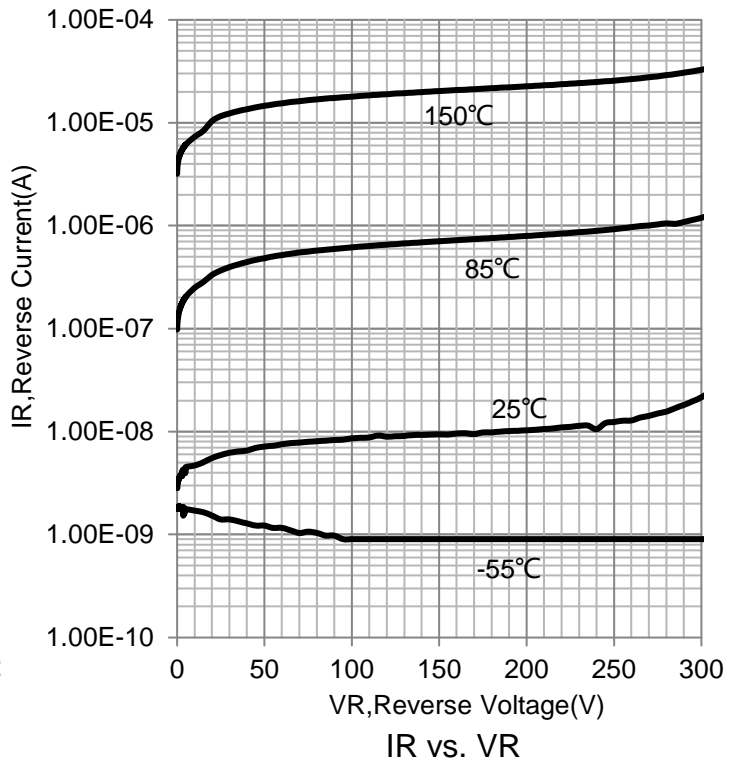
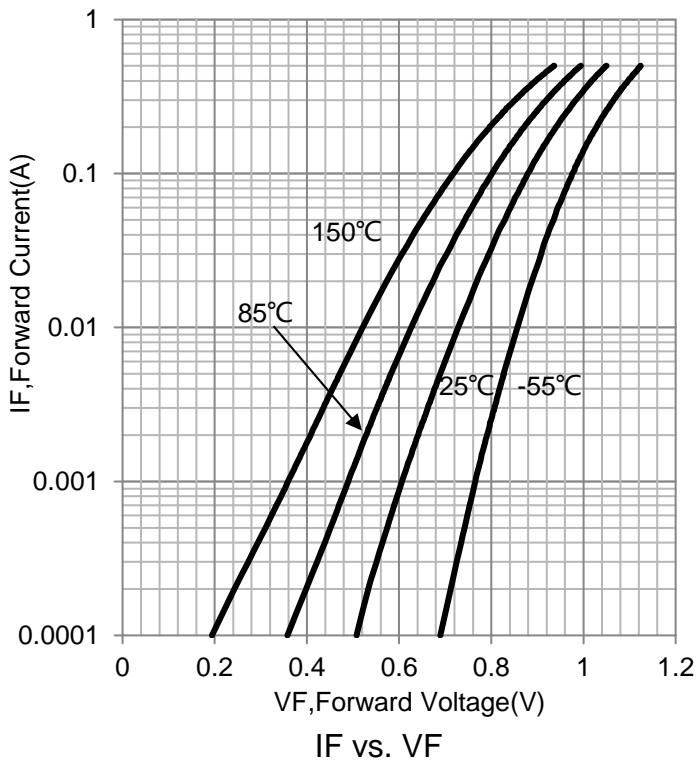
Characteristic	Symbol	Limits	Unit
Total Device Dissipation FR-5 Board(Note 1) TA = 25°C	PD	200	mW
Derate above 25°C		1.57	mW/°C
Thermal Resistance Junction to Ambient	RθJA	635	°C/W
Junction and Storage Temperature Range	TJ,Tstg	-55~+150	°C

1.FR-5 Minimum Pad

### 5. ELECTRICAL CHARACTERISTICS (Ta= 25°C)

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Reverse Voltage Leakage Current (VR = 200 V)	IR	-	-	1	μA
(VR = 200 V, TJ = 150°C)		-	-	100	
Reverse Breakdown Voltage (IBR = 100 μA)	V(BR)	200	-	-	V
Forward voltage (IF =100mA)	VF	-	-	1000	mV
(IF =200mA)		-	-	1250	
Diode Capacitance (VR = 0, f = 1.0 MHz)	CD	-	-	5	pF
Reverse Recovery Time (IF = IR = 30 mA, RL = 100 Ω)	trr	-	-	50	ns

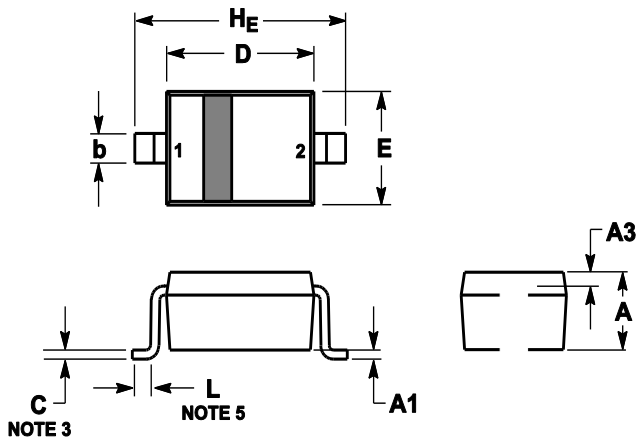
**6.ELECTRICAL CHARACTERISTICS CURVES**



## 7. OUTLINE AND DIMENSIONS

Notes:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.



DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.8	0.9	1	0.031	0.035	0.04
A1	0	0.05	0.1	0	0.002	0.004
A3	0.15REF			0.006REF		
b	0.25	0.32	0.4	0.01	0.012	0.016
C	0.089	0.12	0.177	0.003	0.005	0.007
D	1.6	1.7	1.8	0.062	0.066	0.07
E	1.15	1.25	1.35	0.045	0.049	0.053
L	0.08			0.003		
$H_E$	2.3	2.5	2.7	0.09	0.098	0.105

## 8. SOLDERING FOOTPRINT

